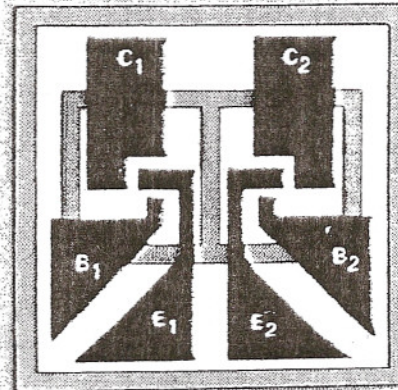




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



20.0 x 20.0 MILS

Topside Metal: Aluminum

Backside Metal: Gold

Backside Potential:

Bond Pad Size: .004" min.

Mask Ref:

APPROVED BY: C Dawson

DIE SIZE : .020" X .020"

DATE: 3/28/06

MFG: Dionics

THICKNESS: .008"

Part # IT122-D